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METHOD FOR ELECTROPLATING METAL

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Inventor: SUGAYA YOSHIO; MATSUMURA YUKIO; MIYAKE HARUHISA
Applicant: ASAHI GLASS CO LTD
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Abstract of **JP6158397**

PURPOSE:To perform the dissolving of metal and the formation of acid in a good balance by installing a metal dissolving tank and a plating tank separately, using an anion exchange membrane in each tank and circulating the acid formed in the dissolving tank through the tanks. **CONSTITUTION:**In a metal dissolving tank 1, the region between an anode 11 consisting of soluble metal and an insoluble cathode 12 is divided by an anion exchange membrane 13 to form an anodic chamber 14 and a cathodic chamber 15. On the other hand, in a plating tank 2, the region between an insoluble anode 21 and a cathode 22 to be plated by an anion exchange membrane 23 to form an anodic chamber 24 and a cathodic chamber 25. In this constitution, the anodic chamber 14 of the metal dissolving tank 1 and the cathodic chamber 25 of the plating tank 2 are connected by a plating liquid circulating circuit 4 through a plating liquid tank 3. And the cathodic chamber 15 of the metal dissolving tank 1 and the anodic chamber 24 of the plating tank 2 are connected by an acidic liquid circulating circuit 6 through an acidic water solution tank 5. Consequently, acid is circulated to perform the dissolving and plating of metal without taking out the acid formed in the metal dissolving tank 1 to outside the system to dissolve metal.

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